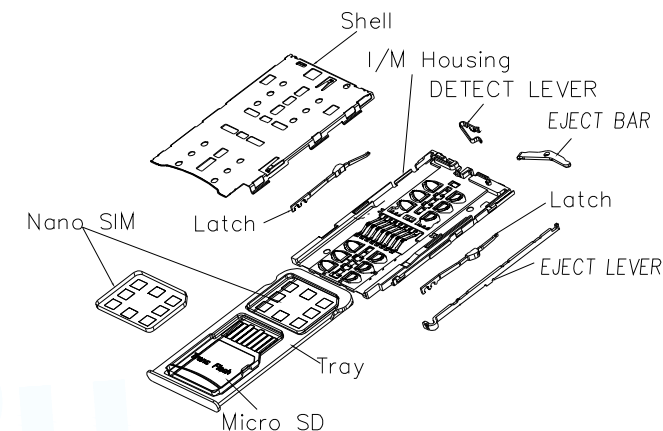


Diagram illustrating the mapping of a 16-bit address to a 32-bit instruction:

- Address fields (16 bits): XX, X, X, XX
- Instruction fields (32 bits):
 - Date: 01,02,03.....
 - Month: A: Jan; B: Feb.....
 - Year: 5: 2015; 6: 2016.....
 - Line: 01,02,03.....



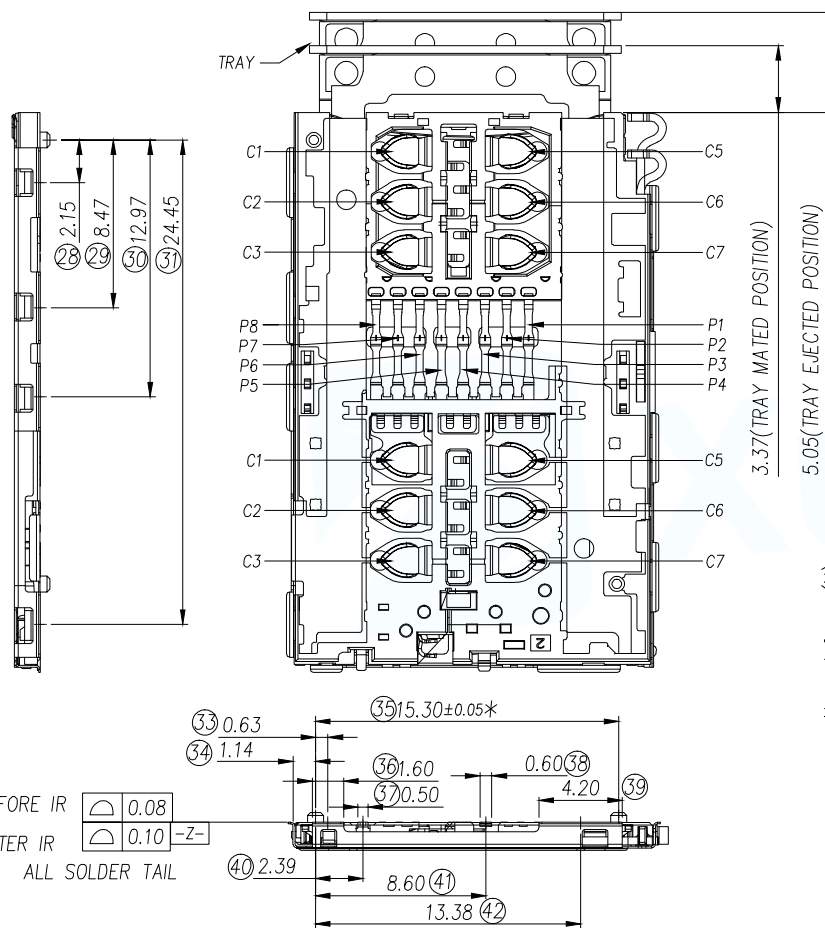
8	LATCH MOLD	PA9T UL94V-0	2	NO PLATING,BLACK PLASTIC
7	LATCH	SUS301-H T=0.30mm	2	NO PLATING
6	DETECT LEVER	C7035-TM06 T=0.15mm	1	3u" Au PLATING ON CONTACT AREA,2u" Au PLATING ON SOLDER TAILS,50u" Min Ni UNDERPLATING OVER ALL
5	EJECT LEVER	SUS304-H T=0.40mm	1	NO PLATING
4	EJECT BAR	SUS304-1/2H T=0.40mm	1	NO PLATING
3	SHELL	SUS301-H T=0.10mm	1	2u" Au PLATING ON SOLDER TAILS, 50u" Min. Ni UNDERPLATING OVER ALL
2	CONTACT	C5240HQ-SH T=0.08mm	1	3u" Au PLATING ON CONTACT AREA , 2u" Au PLATING ON SOLDER TAILS, 50u" Min. Ni UNDERPLATING OVER ALL
1	HOUSING	LCP UL94 V-0	1	PURE MATERIAL,BLACK COLOR
ITEM	NAME	MATERIAL	Q'TY	REMARK

 东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd



PAR	MCS-302L-C1	
DWN		
CHKD		
APVD		
SCALE:1:1	UNIT:MM	
SIZE:A4	SHEET:1F1	REV:A

	SCALE:1:1	UNIT:MM	
CUSTOMER COPY	SIZE:A4	SHEET:1F1	REV:A



NOTES:

1)PRODUCT SPECIFICATIONS:

VOLTAGE RATING:10V

CURRENT RATING:0.5A

INSULATON RESISTANCE:1000 MEG.OHM MIN

CONTACT RESISTANCE:INITIAL 50mΩ MaX;AFTER TEST R=30mΩ

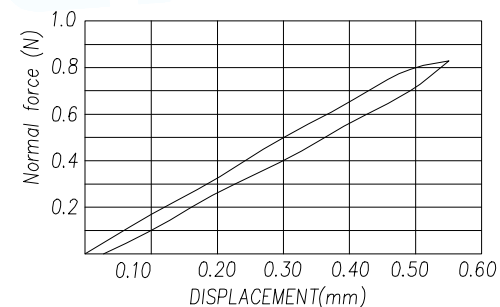
OPERATION TEMPERATURE:-40° TO +85°

DURABILITY:3000 CYCLES

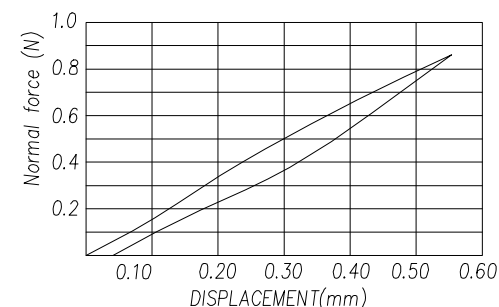
TRAY MATING FORCE:2~10N:TRAY UNMATING FORCE:4~10N

OPERATING FORCE:4~10N

THE RESORPTON DISTANCE OF THE TRAY:0.40mm MIN.



Nano Sim card Contact NF-Deflection Curve



Micro SD Card Contact NF-Deflection Curve

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,LtdUNLESS OTHERWISE
SPECIFIED TOLERANCESTITLE:1.35H 3in2 CONN.DOUBLE
NANO SIM+Micro SD

DECIMALS:

ANGLES:

X.:±0.50

X':±5°

X.X:±0.30

X.X':±3°

X.XX:±0.15

X.XX':±1°

PAR

MCS-302L-C1

DWN

Lucas

CHKD

Ethan

APVD

Jacob

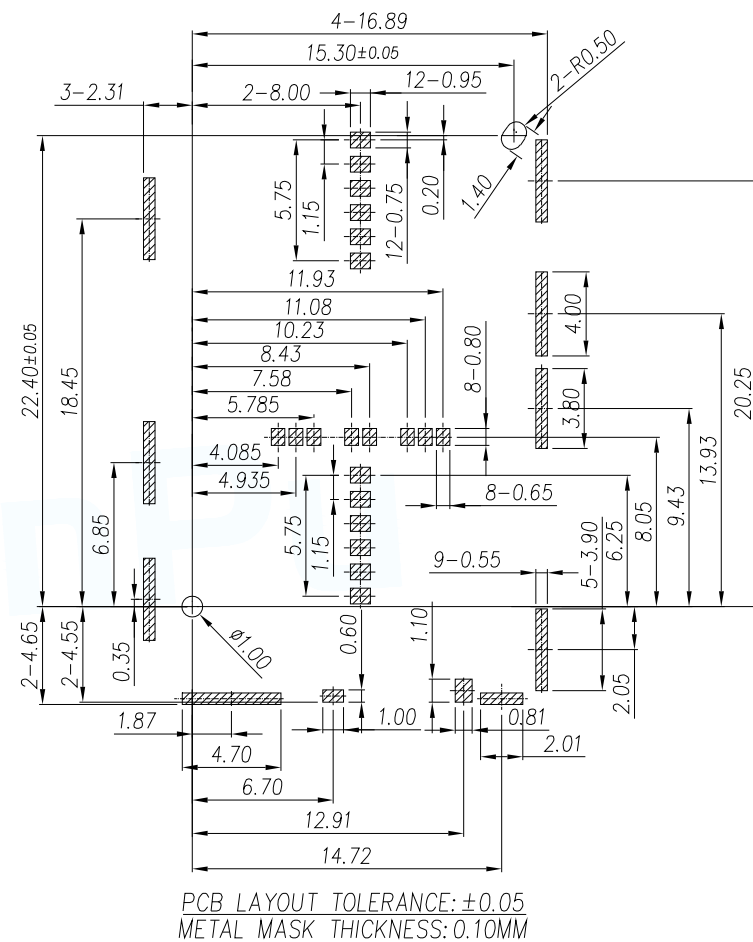
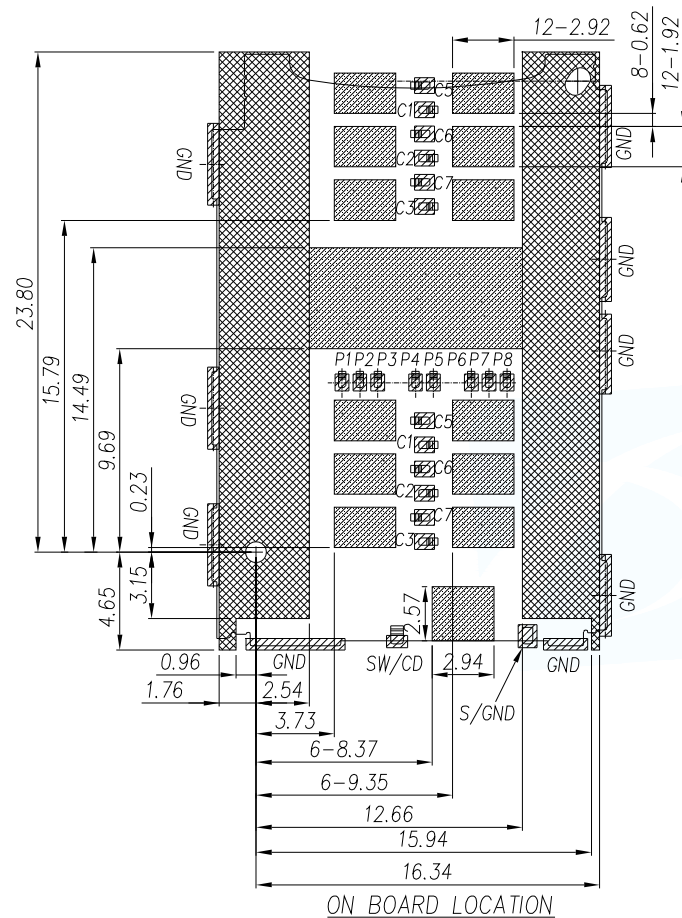
SCALE:1:1

UNIT:MM

SIZE:A4

SHEET:1F1

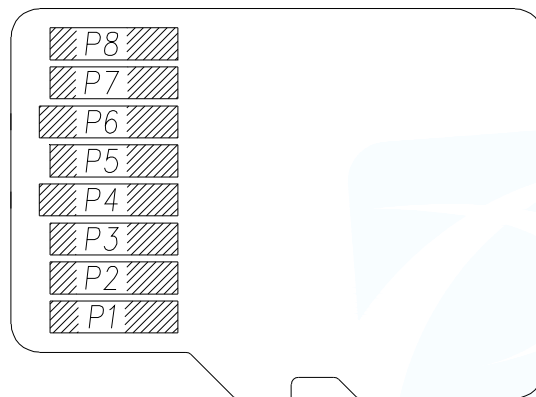
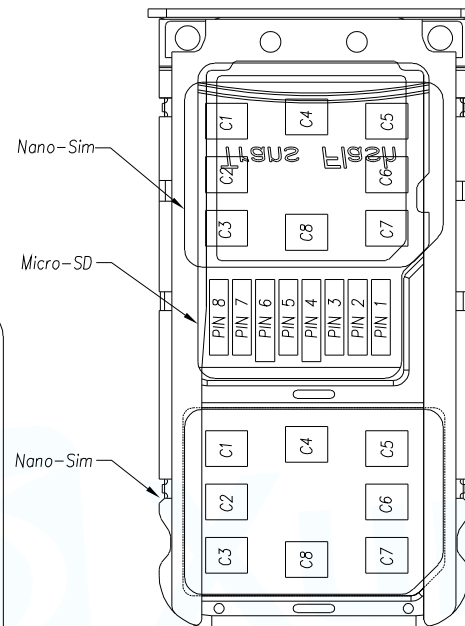
REV:A



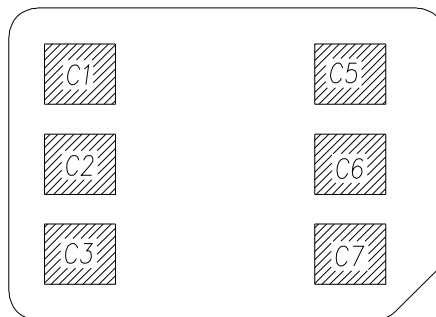
- Through Hole
▨ Soldering Pad Area
▨ Open Wire Restricted Area
(Possibility Touch Of Components On PCB)
▨ No Soldering Pad Area (Independent Pad Area)
OR Open Wire & Copper Restricted Area
1: Touch area of contact tips, No electrical function and only for mechanical func
2: No first PCB-Layout circuits in the area.

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD		
			PAR	MCS-302L-C1	
DECIMALS:	ANGLES:		DWN		
X.:±0.20	X'':±2°		CHKD		
X.X:±0.15	.X':±1°		APVD		
X.XX:±0.10			SCALE:1:1	UNIT:MM	
		CUSTOMER COPY	SIZE:A4	SHEET:1F1	
				REV:A	

BOTTOM VIEW



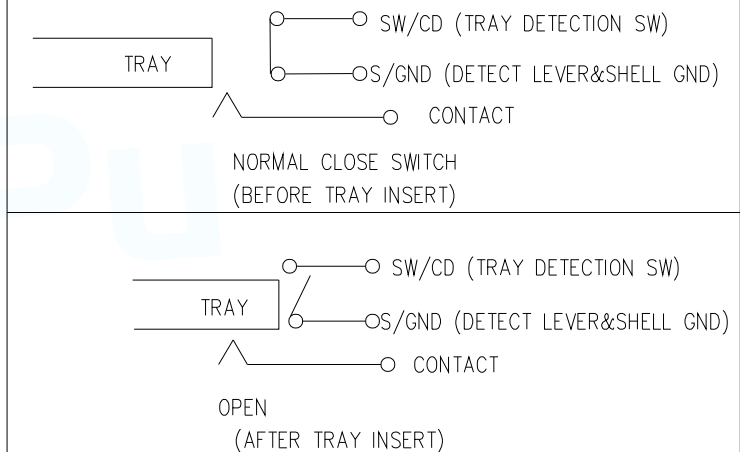
Micro SD CARD ELECTRICAL



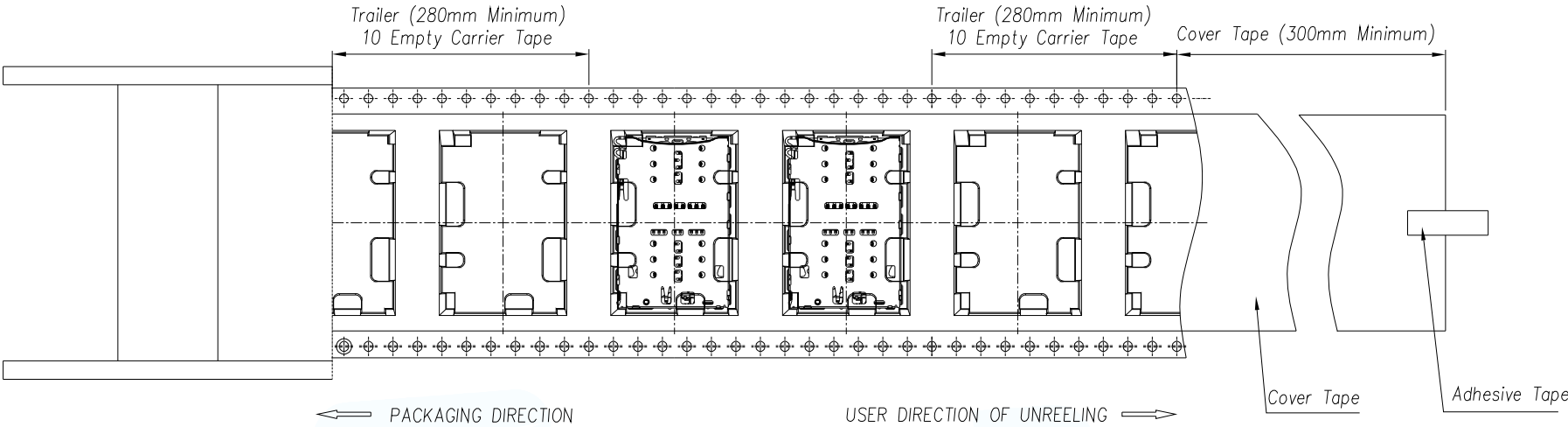
NANO SIM CARD ELECTRICAL

ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

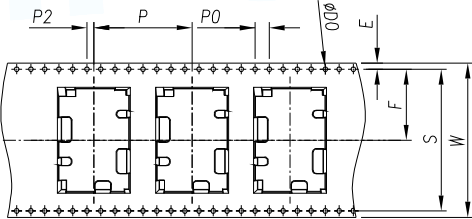
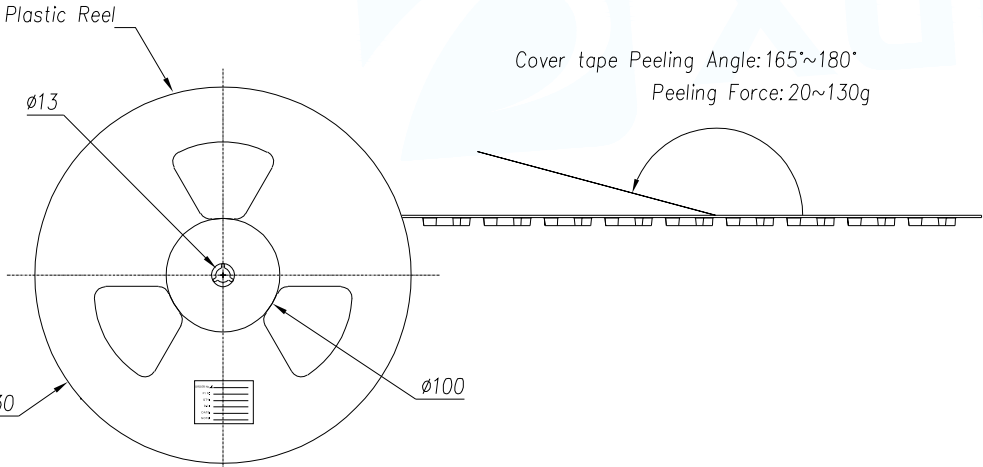
CIRCUIT DIAGRAM FOR DETECT SWITCHES



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			
DECIMALS:	ANGLES:	TITLE: 1.35H 3in2 CONN. DOUBLE NANO SIM+Micro SD	
X.:±0.20	X'.:±2°	PAR	MCS-302L-C1
X.X:±0.15	.X':±1°	DWN	
X.XX:±0.10		CHKD	
CUSTOMER COPY		APVD	
		SCALE:1:1	UNIT:MM
		SIZE:A4	SHEET:1F1
			REV:A



P	28.00±0.10
P0	4.00±0.10
P2	2.00±0.10
D0	1.50±0.10
E	1.75±0.10
F	20.20±0.10
S	40.40±0.10
W	44.00±0.10



1	MCS-302L-C1	800	6	9.95	4800	340X340X335
ITEM	PRODUCT NO:	QTY/REEL	REEL/CARTON	Kg/CARTON	QTY/CARTON	CARTON SIZE

MANUFACTURE DWG

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:

ANGLES:

X.:±0.20

X'.:±2°

X.X:±0.15

.X':±1°

X.XX:±0.10



东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

TITLE: 1.35H 3in2 CONN.
DOUBLE NANO SIM+Micro SD

PAR

MCS-302L-C1

DWN

CHKD

APVD

SCALE1:1

UNIT:MM



CUSTOMER COPY

SIZE:A4

SHEET:1F1

REV:A